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EXPRESS MAIL NO.: EV 346 795 107 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Christophe MALEVILLE et al.

Confirmation No.5090

Application No.: 10/808,288

Group Art Unit: 2812

Filing Date: March 25, 2004

Examiner: Stanetta D. Isaac

For: METHOD FOR PREPARING A BONDING
SURFACE OF A SEMICONDUCTOR LAYER OF
A WAFER

Atty. Docket No.: 4717-10500

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

In response to the final office action dated December 15, 2005, please enter the following amendments and comments into the file of this application.

No amendments to the claims are presented herewith.

Remarks begin on page 2 of this paper.

No fees are believed to be due with this response. Should any fees be required to process this amendment, however, please charge them to Winston & Strawn LLP Deposit Account No. 50-1814.